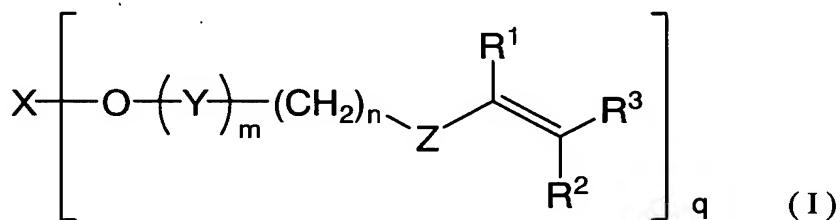


Abstract of The Disclosur

An object of the invention is to provide a poly(phenylene ether) resin composition that allows production of laminated sheets excellent in heat resistance and processability, even in case of using a low molecular weight PPE for convenience in prepreg manufacturing without the sacrifice of dielectric characteristics.

The poly(phenylene ether) resin composition according to the present invention comprises poly(phenylene ether) and a crosslinking curing agent, wherein the poly(phenylene ether) is represented by the following formula (I) and the number averaged molecular weight thereof is in the range of 1,000 to 7,000.



[wherein, X is an aryl group; $(Y)_m$ is a poly(phenylene ether) moiety; Z is a phenylene group and the like; R^1 to R^3 each independently is a hydrogen atom, and the like; n is an integer of 1 to 6; and q is an integer of 1 to 4.]